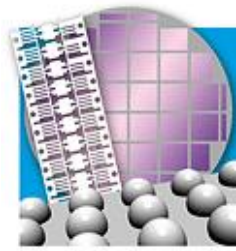


HYDRON® SE 230A

alkaline defluxing agent for semiconductor electronics



HYDRON® SE 230A is a water-based, single-phase cleaning agent specifically developed for the use in dip tank processes. HYDRON® SE 230A reliably removes flux residues from all kind of semiconductor electronics, such as leadframes, discrete devices, power modules and power LEDs as well as flip chip or CMOS, i.e. after die attach. It provides excellent deoxidation of Cu substrates for subsequent processes such as wire bonding or molding.

Areas of application: defluxing of semiconductor electronics (leadframes, discrete devices, power modules & -LEDs, flip chip, CMOS)			Additional product information:
Solder Paste	Low solids	+	Technical Information 3: Material compatibility overview
	Water-soluble (OA)	++	
	No clean	++	
	High solids	++	
	Lead-based	+	

++ highly recommended, best results + recommended 0 possible - not recommended

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Advantages compared to other cleaners:

- HYDRON® SE 230A provides stainless, activated copper surfaces for subsequent processes such as wire bonding, moulding and adhesive bonding and retains these activated surfaces over a temporary storage time.
- The cleaner shows a high level of material compatibility on sensitive materials such as copper, aluminum and specifically nickel
- Featuring a very low surface tension, it works exceptionally well for cleaning capillary spaces, i.e. underneath low stand-off components
- Due to its single-phase formulation, HYDRON® SE 230A can be easily processed and provides excellent performance in dip tank processes.
- It can be easily rinsed off with DI-water without leaving any residues
- HYDRON® SE 230A has no flash point, is formulated free of halogenated compounds and has a low odor.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.



Process Steps	1. Cleaning	2. Rinsing	3. Drying
Ultrasonic (US) / Spray under immersion (SUI)	HYDRON® SE 230A	DI-water ¹	Hot air or circulating air

¹The DI-water temperature should be between 20-40°C/68-104°F.

Technical Data		
Please note that the following information represents HYDRON® SE 230A at 15 % concentration.		
Density	(g/ccm) at 20°C/68°F	0,99
Surface tension	(mN/m) at 25°C/77°F	27,7
Boiling point	°C/°F	>98°C / > 208°F
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	9,60
Vapor pressure	(mbar) at 20°C/68°F	Approx. 20
Cleaning temperature	°C/°F	40 - 60°C / 104 - 140°F
Solubility in water		Soluble
Application concentration ¹	Concentrate	15-25%

¹The concentrate of HYDRON® SE 230A has to be diluted in DI-water.

PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



Product is free of any critical substances according to SIN & SVHC lists



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Filter recommendation

- To take full advantage of the cleaner and further expand the bath life of HYDRON® SE 230A, filtration is recommended.

Environmental, health and safety regulations:

- HYDRON® SE 230A is water-based and biodegradable.
- HYDRON® SE 230A is formulated free of any halogenated compounds and environmentally friendly.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- HYDRON® SE 230A is available as a concentrate in 1l bottles, 5l or 25l containers and 200l drums.
- Store HYDRON® SE 230A in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

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